	T15XB (20~80)	版本号: V1.0
	桥式整流器	

产品概述 General Description

整流桥堆产品是由四只整流硅芯片作桥式连接，外用绝缘塑料封装而成。

The rectifier bridge heap product is made by four the rectifier silicon chip as a bridge to connect the topical insulated plastic package

产品特点 (Features)

- 玻璃钝化芯片

Glass passivated chip

- 耐正向浪涌电流高

High surge forward current capability

应用领域 (Applications)

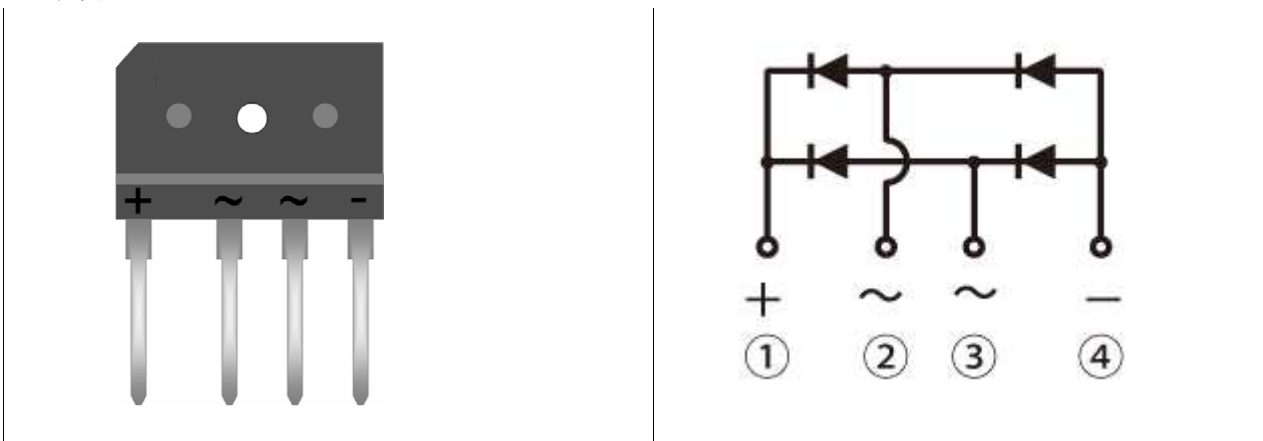
作一般电源单相桥式整流用。

General purpose 1 phase Bridge rectifier applications

特征参数 (Characteristic parameters)

符合 Symbol	额定值 Ratings	单位 Unit
VRRM	200-800	V
I _o	15	A

封装:



极限值 (除非另有规定, $T_a=25^\circ\text{C}$)

Limiting Values (unless otherwise specified $T=25^\circ\text{C}$)

参数名称 Parameter	符号 Symbol	条件Conditions	T15XB				单位	
			20	40	60	80		
反向重复峰值电 Repetitive Peak Reverse Voltage	VRRM		200	400	600	800	V	
平均整流输出电流 Average Rectified Output Current	I_o	50Hz正弦波, 电阻负载 50HZ sine wave, R-load	用散热片 $T_c=100^\circ\text{C}$ With heat sink $T_c=100^\circ\text{C}$				15	A
			无散热片 $T_a=25^\circ\text{C}$ Without heat sink $T_a=25^\circ\text{C}$				3.2	
正向不重复浪涌电 Surge(Non-repetitive)Forward Current	I_{FSM}	50HZ正弦波, 一个周期, $T_a=25^\circ\text{C}$ 50HZ sine wave, 1 cycle, $T_a=25^\circ\text{C}$	200				A	
贮存温度 Storage Temperature	T_{stg}		-40 ~ +150				$^\circ\text{C}$	
结温 Junction Temperature	T_j		+150				$^\circ\text{C}$	
绝缘耐压 Dielectric Strength	Vdis	端子与外壳之间外加交流电, 一分钟 Terminals to case, AC 1 minute	2.5				kV	
安装扭矩 Mounting Torque	TOR	推荐值: 5kg·cm Recommend torque: 5kg·cm	8				kg·cm	

电特性 (除非另有规定, $T_a=25^\circ\text{C}$)

Electrical Characteristics ($T_a=25^\circ\text{C}$ Unless otherwise specified)

参数名称 Parameter	符号 Symbol	测试条件 Test Condition	最大值 MAX	单位
正向峰值电压 Peak Forward Voltage	VFM	$I_{FM}=7.5\text{A}$, 脉冲测试, 单个二极管的额定值 $I_{FM}=7.5\text{A}$, Pulse measurement, Rating of per diode	1.1	V
反向峰值电流 Peak Reverse Current	IRRM	$V_{RM}=V_{RRM}$, 脉冲测试, 单个二极管的额定值 $V_{RM}=V_{RRM}$, Pulse measurement, Rating of per diode	10	μA
	$R_{\theta J-A}$	结和环境之间, 无散热片 Between junction and ambient, Without heatsink	22	$^\circ\text{C}/\text{W}$
热阻 Thermal Resistance	$R_{\theta J-L}$	结和引线之间, 无散热片 Between junction and lead, Without heatsink	5	
	$R_{\theta J-C}$	结和管壳之间, 用散热片 Between junction and case, With heatsink	1.5	

典型特性曲线(Characteristics)

■ 特性曲线 (典型) Characteristics(Typical)

